

XFEL Crate Standard Workshop

Requirements

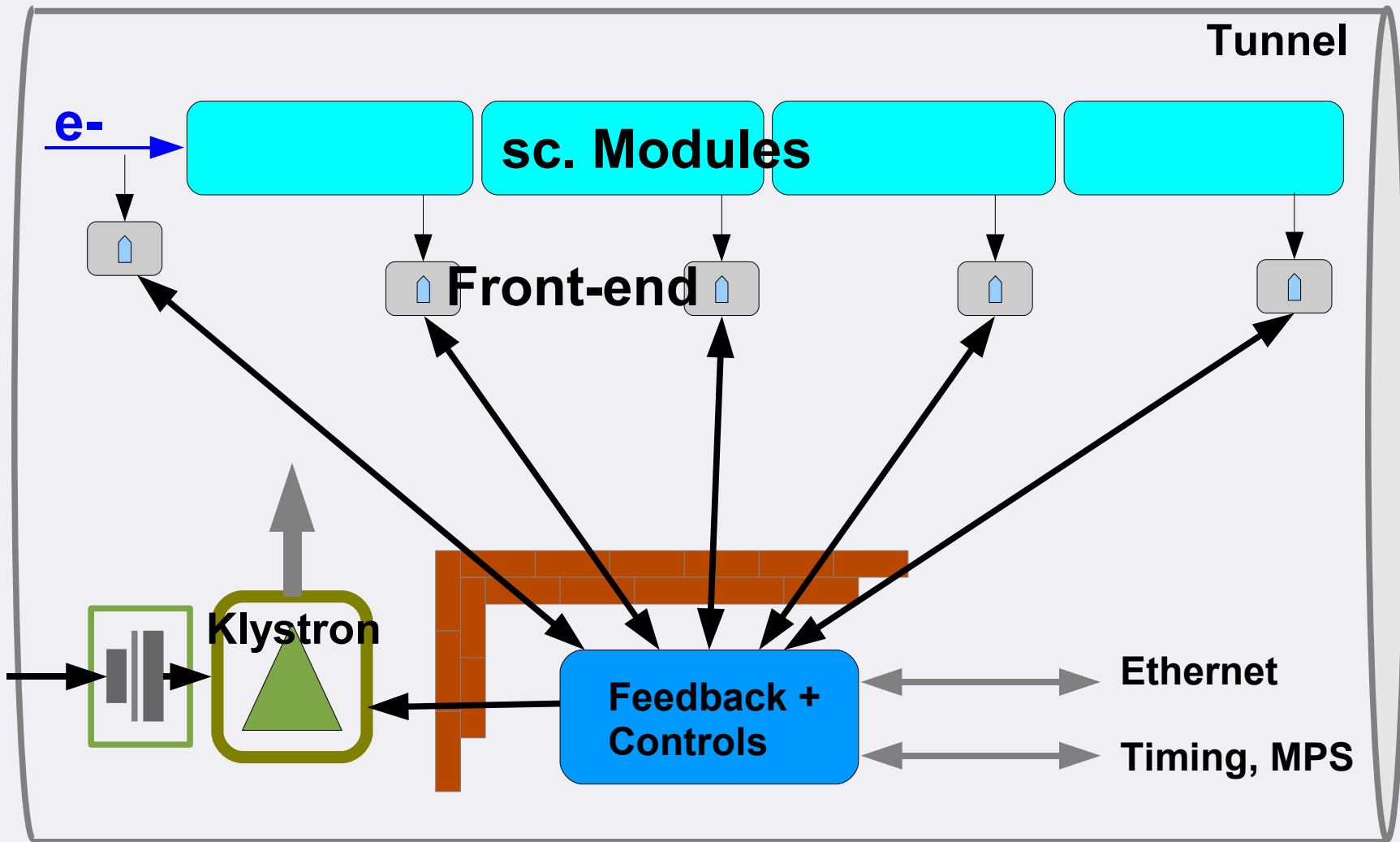
Possible solutions

Kay Rehlich

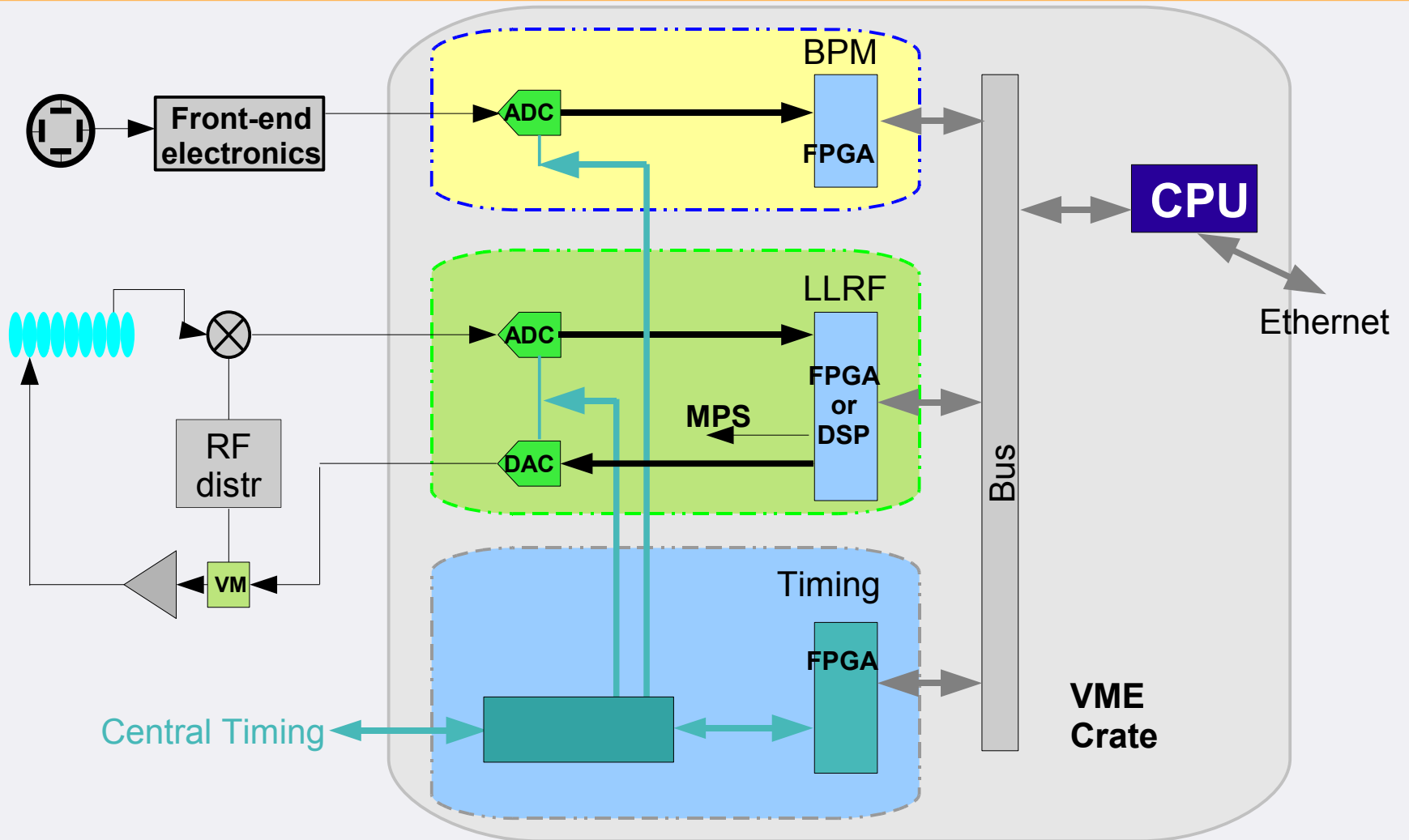
Motivation

- Consistent data acquisition of all XFEL sub-systems
- Manageable and reliable system
- Find today a solution with support for the next 10 years
- Can we agree on common hardware, interfaces and software for the XFEL?

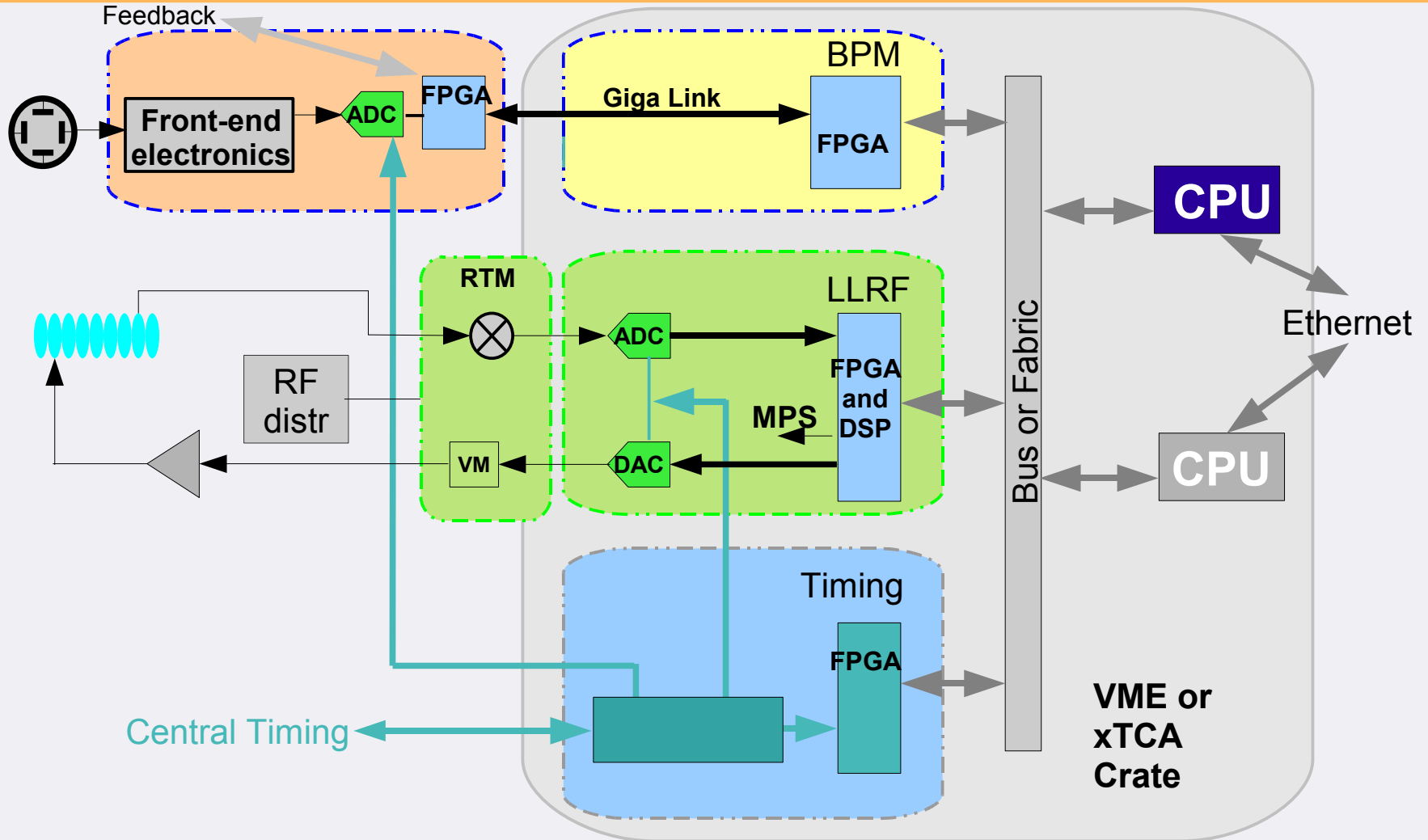
Geographical Layout



The Front-end: **FLASH** Example

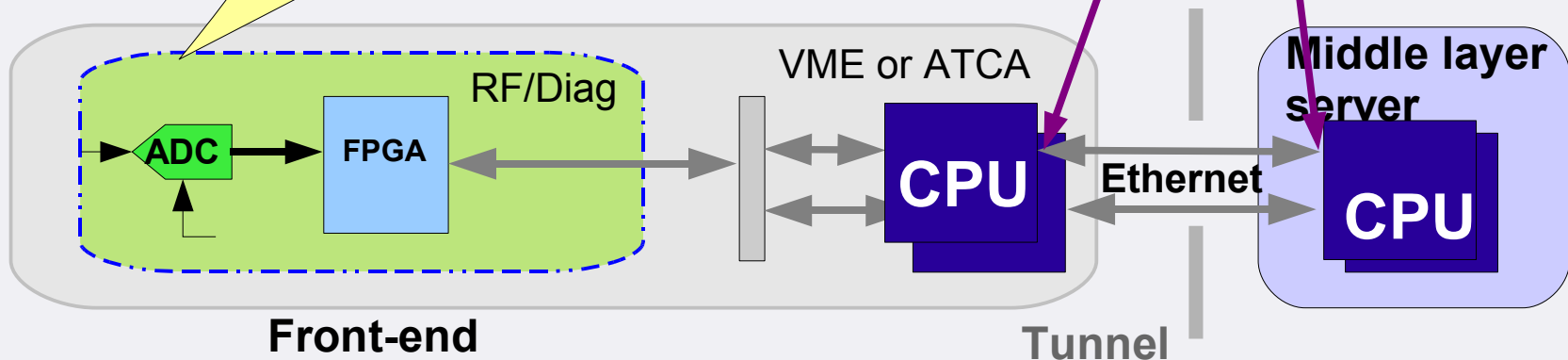
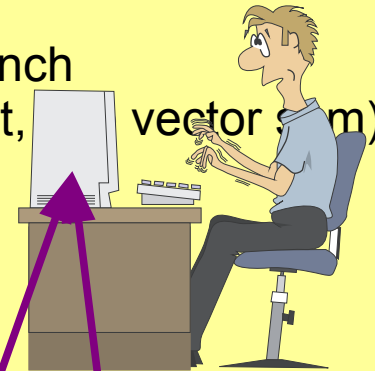


The Front-end: Alternatives



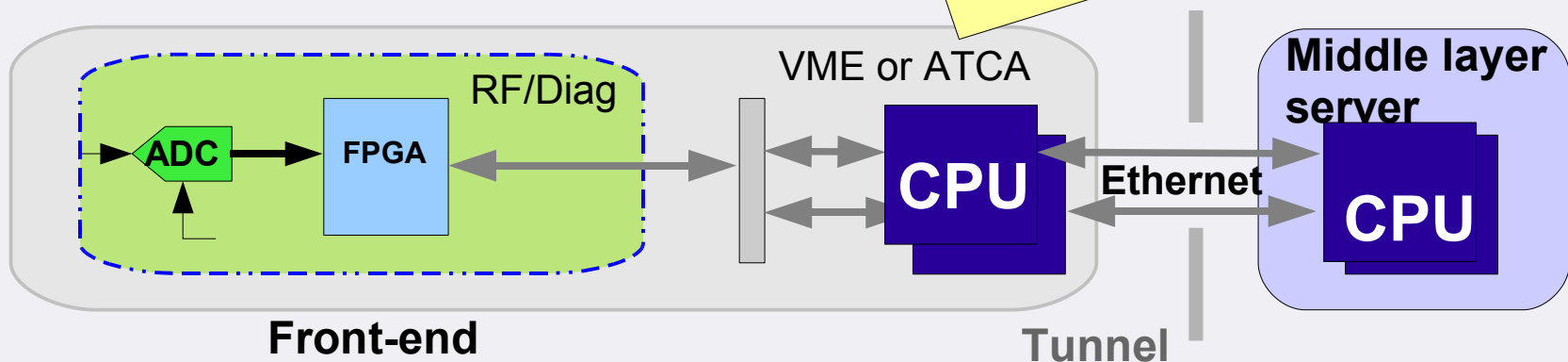
Data Flow: Front-end

- Preprocessing: **reduce data** to e.g. one set per bunch channel based calculations (e.g. peak detect, vector sum)
- Timing: adjust clock and triggers
- Program (FPGA) loading and verification
- Feedback algorithm
- Data buffer (several XFEL shots)
- Self-tests / calibrations
- Provide debug data (e.g. full samples) on request



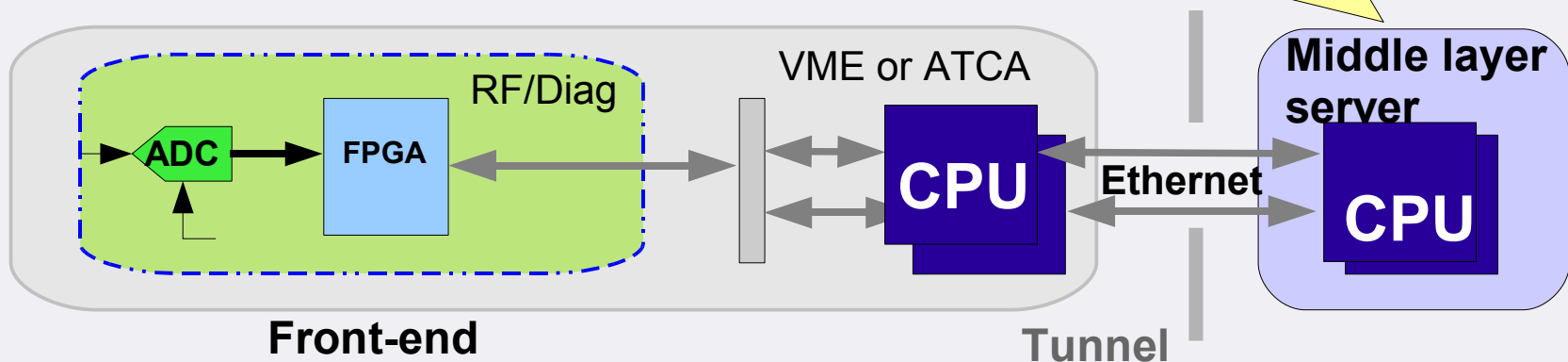
Data Flow: Device Server

- DOOCS device server process
- Data buffer for the control system
- 'self-healing' of the feedback and diagnostics controllers: check/restart programs, parameters and processors
- State machines
- 'fail-over' control (e.g. feedforward only operation)
- Redundant CPU possible (ATCA)
- Auto tuning cavity f, adaptive feedforward, loop phase, calibrations



Data Flow: Service Tier

- **Global services** (for multiple devices)
- Alarming
- Automation (start-up, optimization, calibration, operation..)
- Data Acquisition
- Slow feedbacks
- Global momentum manager or global orbit ...



Requirements (1)

- **Must provide a connection to the XFEL timing/clock system (hardware and software)**
- **Ethernet as data transport and controls network**
- **Performance**
 - ➔ data transfer speed (different requirements of subsystems)
 - ➔ analog signal quality
- **Modular**
 - ➔ same components usable in different XFEL subsystems
- **Common software interface**
 - ➔ similar solutions for different subsystems

Requirements (2)

- **Reliability and availability**

- ➔ high MTBF
- ➔ redundancy for components with lower MTBF (e.g. fans)
- ➔ redundancy for central systems (e.g. Timing, MPS)

- **Decoupled**

- ➔ no single point of failure
- ➔ no influence between subsystems (e.g. one module in a crate should not harm others)

Requirements (3)

- **Hot-swap**
 - ➔ if more than one subsystem uses the same crate
- **Maintainable: safe exchange of modules**
 - ➔ Without opening boxes etc.
 - ➔ Cable connections (few at front, rear if possible)
- **Remote manageable**
 - ➔ Detection of all crates and modules
 - ➔ reset and other commands to modules
- **Good fault diagnosis**
 - ➔ detect defect or degraded modules

Requirements (4)

- **Costs**

- ➔ Compatible with XFEL budget book
- ➔ Should allow high and low end solutions

- **Development effort**

- ➔ Number of modules to be [re]designed for the XFEL
- ➔ Experience of developers

- **Common parts available from industry (e.g. crates, CPUs, I/O)**

- **RoHS compliant**

- **Life time of the products (new developments) > 2014**

Possible Solutions

- **VME (+ VXS...)**
- **xTCA (ATCA + μ TCA)**
- **cPCI**
- **Network attached devices**
- **...**

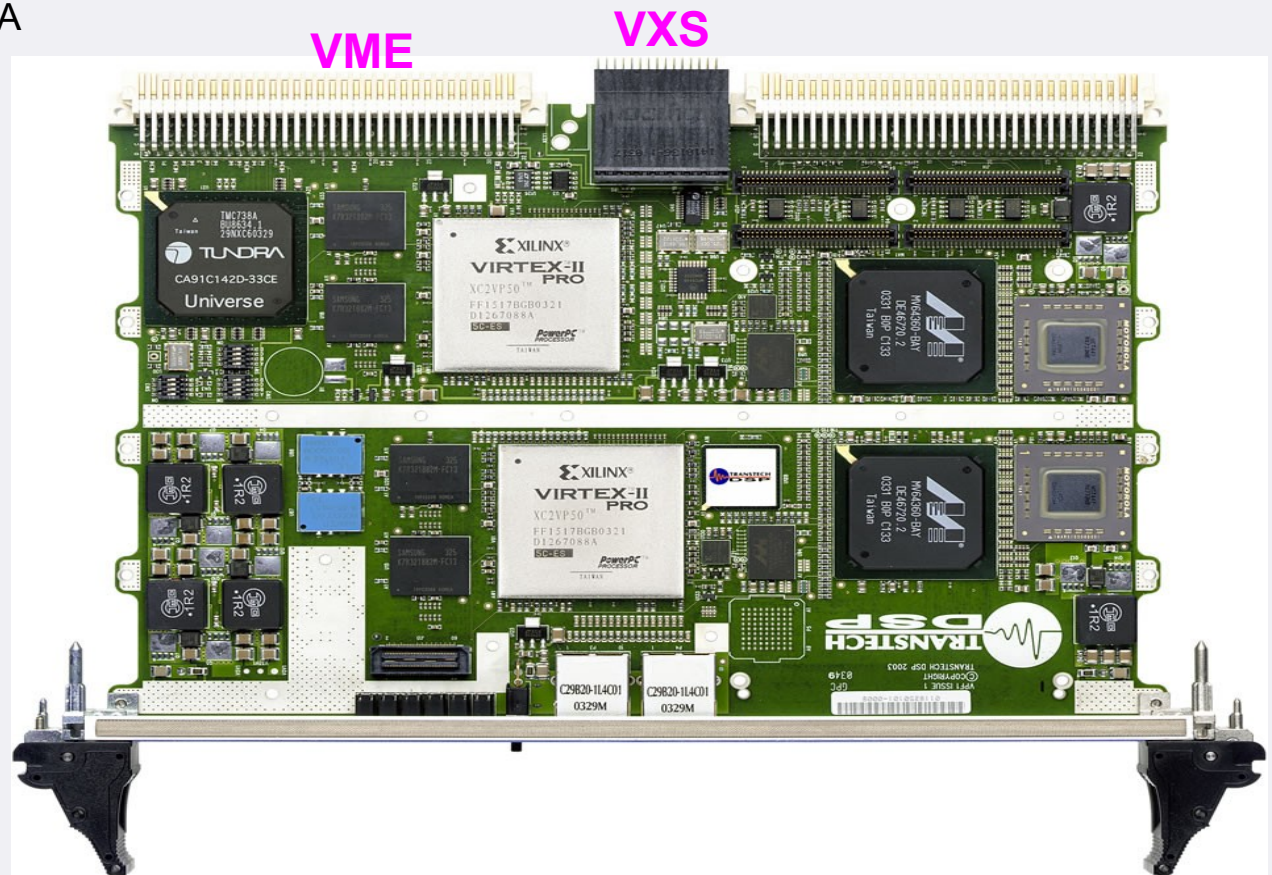
Possible Solutions: VME

Example

- 2x PowerPC 7447 CPU nodes
- 2x Xilinx Virtex-II Pro FPGA
- 8X 2.0-3.125 Gbit/sec VMETRO

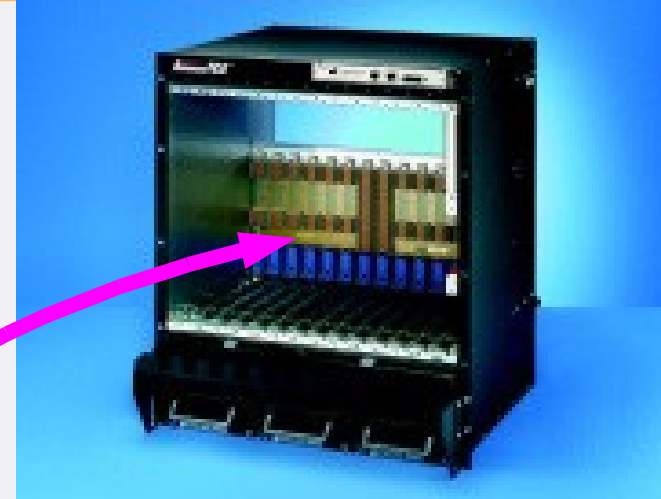
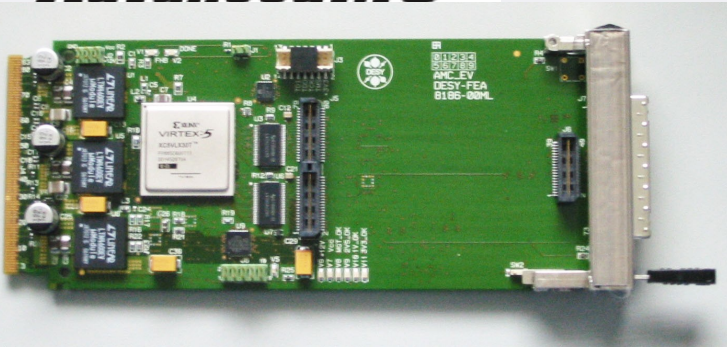
> 40 VME Crates
@ FLASH

since 1993

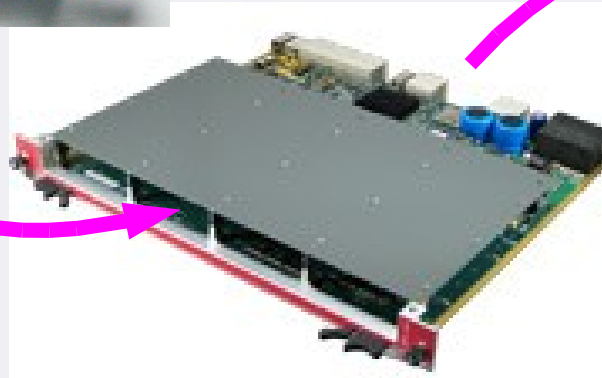


Possible Solutions: xTCA

AdvancedMC™



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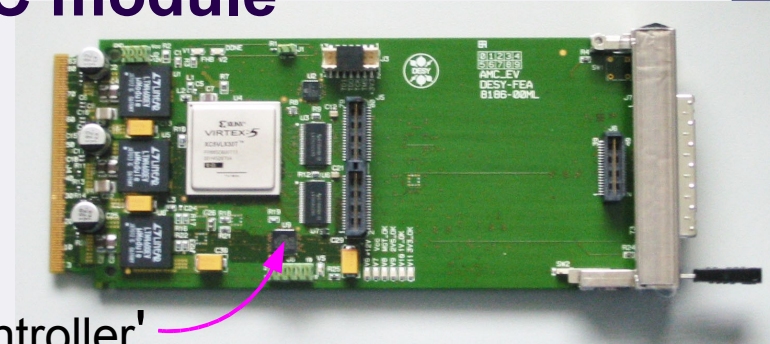


μTCA™



xTCA Evaluation

- **Evaluation of industrial products (crates, CPUs, IO)**
- **Ordering of a AMC module (DESY specs)**
 - ➔ ADC with 8 ch., 100 MHz, 14 bit
 - ➔ not yet ready: problem with CAD for PCB layout
- **Development of an universal AMC module**
 - ➔ FPGA code with PCIe interface
 - ➔ DOOCS server and OS driver
 - ➔ IPMI DOOCS server and displays
 - ➔ IPMI code for 'Module Management Controller'
 - ➔ Piggy-back with 2 ADC and 2 DAC channels in preparation
- **More Projects for LLRF --> S. Simrock talk**



Objectives for the workshop

- **Requirements for the electronics of the XFEL**
 - ➔ general and for specific subsystems
- **Discussion of possible solutions**
- **Experience reports for different solutions**
- **Market development for standard crates and modules**
- **Comparison of the solutions with respect to the requirements**